

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
FUMITOMO WATANABE	01/25/2017
KEIYO KUSANAGI	01/28/2017
<b>RECEIVING PARTY DATA</b>	
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16154659
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<b>NAME OF SUBMITTER:</b>	SAM BEARD
<b>SIGNATURE:</b>	/Sam Beard/
<b>DATE SIGNED:</b>	10/08/2018
<b>Total Attachments: 4</b>	
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### ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Fumitomo Watanabe, having a mailing address of c/o Micron Akita, Inc.89-2, Yamada, Yuwaishida, Akita-shi Akita, 010-1222 Japan; and
- Keiyo Kusanagi, having a mailing address of c/o Micron Akita, Inc.89-2, Yamada, Yuwaishida, Akita-shi Akita, 010-1222 Japan.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH DIE SUBSTRATE EXTENSIONS, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings;

or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

Date: 1/25/2017

Fumitomo Watanabe  
Fumitomo Watanabe

Witness:

Shori Fujiwara  
Printed Name

Shori Fujiwara  
Signature

Witness:

Shoko Tomita  
Printed Name

Shoko Tomita  
Signature

Date: 1 / 28 / 2017

Keiyo Kusanagi  
Keiyo Kusanagi

Witness:

Yasuhiro Yama  
Printed Name

Yasuhiro Yama  
Signature

Witness:

Shoko Tomita  
Printed Name

Shoko Tomita  
Signature